


SCALE 25:1

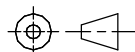
Notes: (Unless Otherwise Specified).

- 1) DIE MATERIAL IS SILICON.
- 2) DIE THICKNESS IS 250 μm (10 MIL).
- 3) METALLIZATION 1.0 μm ALUMINUM (Al) OVER 0.75 μm SiO_2 .
- 4) DIE IS WITHOUT PASSIVATION.
- 5) WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
- 6) ISOLATED PADS 60 μm SQUARE (16 PLACES).
- 7) TOLERANCE = $\pm 1 \mu\text{m}$.

DIMENSIONS IN MICRONS
1000 μm = 1.0mm

PART NUMBER SYSTEM						
TD	-	16	-	1.0	-	ISO
SILICON TEST DIE	BOND PADS	DIE SIZE (mm)	ISOLATED PADS			

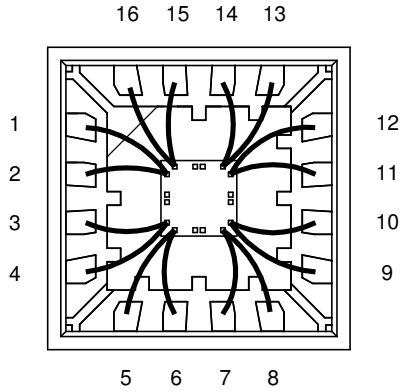
TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.XX	+/- 0.01	DRAWN J. HINES	5/2/2010				
X.XXX	+/- 0.005						
X.XXXX	+/- 0.0005	ENG		SCALE 100:1			
ANGLES	+/- 0.5°	MFG					
ALL DIMENSIONS IN		QA		DO NOT SCALE DRAWING			
☑ INCHES ☐ MILLIMETERS		CUST					
THIRD ANGLE PROJECTION		REVISED					



DAISY CHAIN WIRE BOND PATTERNS QFN PACKAGE

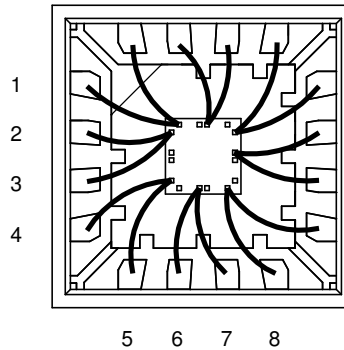
NET LIST DCW10161

- 1-2
- 3-4
- 5-6
- 7-8
- 9-10
- 11-12
- 13-14
- 15-16



QFN16W.65-DCW10161
16L - 4X4mm

16 15 14 13



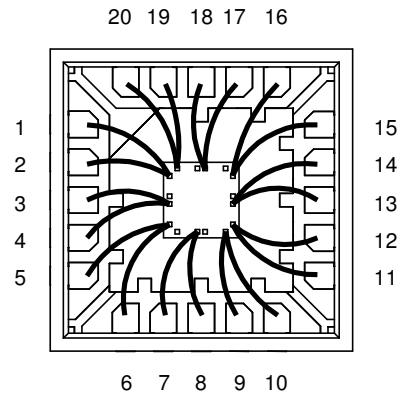
QFN16W.65-DCW10162
16L - 4X4mm

NET LIST DCW10082

- 2-3
- 4-5
- 6-7
- 8-9
- 10-11
- 12-13
- 14-15
- 16-1

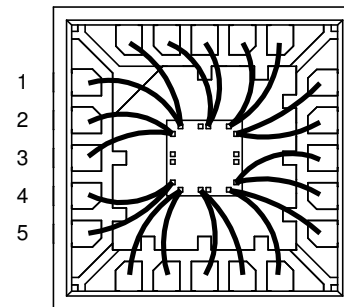
NET LIST DCW10201

- 1-2
- 3-4
- 5-6
- 7-8
- 9-10
- 11-12
- 13-14
- 15-16
- 17-18
- 19-20



QFN20W.5-DCW10201
20L - 4X4mm

20 19 18 17 16



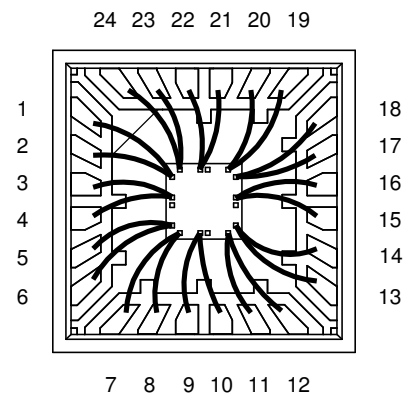
QFN20W.5-DCW10202
20L - 4X4mm

NET LIST DCW10202

- 2-3
- 4-5
- 6-7
- 8-9
- 10-11
- 12-13
- 14-15
- 16-17
- 18-19
- 20-1

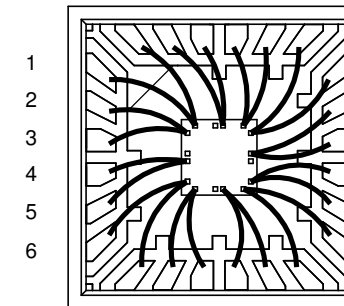
NET LIST DCW10241

- 1-2
- 3-4
- 5-6
- 7-8
- 9-10
- 11-12
- 13-14
- 15-16
- 17-18
- 19-20
- 21-22
- 23-24



QFN24W.5-DCW10241
24L - 4X4mm

24 23 22 21 20 19



QFN24W.5-DCW10242
24L - 4X4mm

NET LIST DCW10242

- 2-3
- 4-5
- 6-7
- 8-9
- 10-11
- 12-13
- 14-15
- 16-17
- 18-19
- 20-21
- 22-23
- 24-1

DIMENSIONS IN MICRONS
1000 μm = 1.0mm

TEST DIE						
TD	-	16	-	1.0	-	ISO
SILICON TEST DIE		BOND PADS		DIE SIZE (mm)		ISOLATED PADS

TopLine [®]			
TITLE		SI TEST DIE TD SERIES	
SCALE	SIZE	DRAWING NO.	REV
10:1	A	151016	A
DO NOT SCALE DRAWING		SHEET 2 OF 2	